

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N06S4-15	**Issued**	31. March 2021
MA#	MA001064538		
Package	PG-TDSON-8-4	**Weight***	97.38 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.345	1.38	1.38	13812	13812
chip_2	inorganic material	silicon	7440-21-3	1.345	1.38	1.38	13812	13812
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		137	
	non noble metal	iron	7439-89-6	0.044	0.05		457	
	non noble metal	copper	7440-50-8	44.409	45.59	45.65	456026	456620
wire	non noble metal	aluminium	7429-90-5	0.749	0.77	0.77	7689	7689
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		915	
	plastics	epoxy resin	-	6.327	6.50		64970	
	inorganic material	silicondioxide	60676-86-0	38.140	39.17	45.76	391651	457536
leadfinish	non noble metal	tin	7440-31-5	1.308	1.34	1.34	13428	13428
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	493	494
solder	non noble metal	tin	7440-31-5	0.066	0.07		682	
	noble metal	silver	7440-22-4	0.083	0.09		852	
	non noble metal	lead	7439-92-1	3.170	3.26	3.42	32556	34090
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.245	0.25	0.25	2515	2519
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com